LV3045BCT

Rev.F May.-2016

WR0596 ṂṂ Ŀ ≠ g⁀ ǁ ᒉ

Schottky Barrier Diode in a TO-263 Plastic Package.

Ḩ* ᵇ ᴙ ں ı Ḩ ı ᾰ̋ ı ῷ ' ڪ

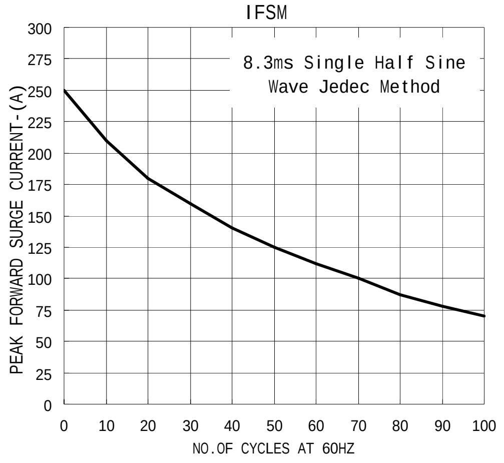
Low forward voltage drop,low power losses,High efficiency operation.

ڪ إ ' ڱ ψ ᴴ ı Ȁ ҥ ɔ ◊ ı ﾊ ╙ ǁ ᒉ ı RU0lq j ⁀ ǁ ᒉ ı GF0GF چ Ώ ᴴ ⊐ ɔ – ɼ ᵇ З ĭ

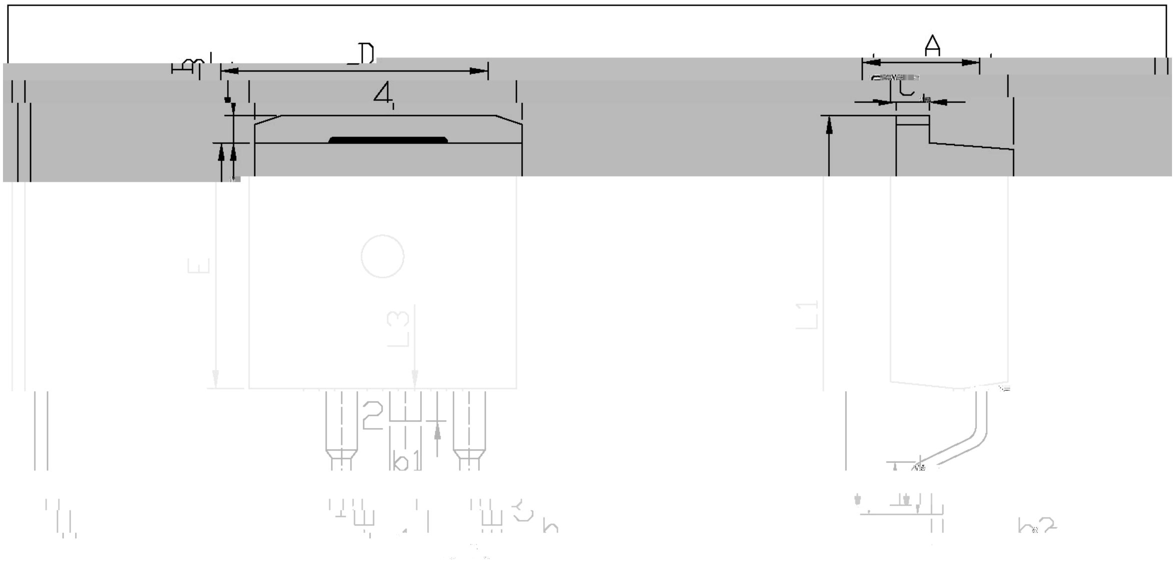
For use in high frequency inverters, switching power supplies, freewheeling diodes, OR-ing diode, dc-to-dc converters and re

v ‶Ω̣ Parameter	ɏ ᴺ Symbol	‶Ω̣Ӫ Rating	D Ʉ

/ Electrical Characteristic Curve



/ Package Dimensions



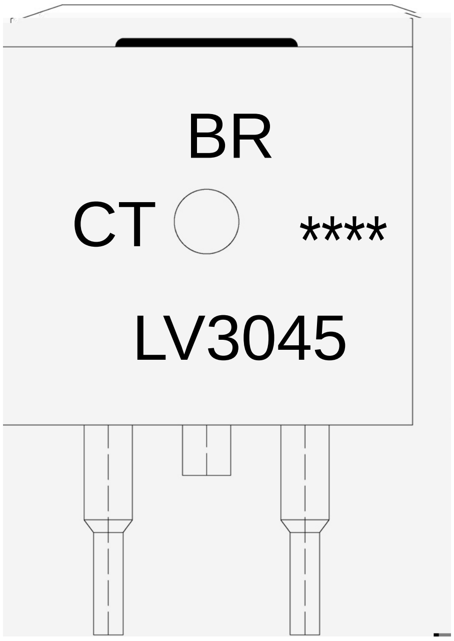
单位：m

Symbol	Min	Max	Symbol	Min	Max
A	4.30	4.70	E	9.00	9.40
B	1.00	1.40	e1	2.34	2.74
b	0.70	0.90	e2	4.88	5.28
b1	1.15	1.35	L1	15.00	16.00

-263

TO

/ Marking Instructions



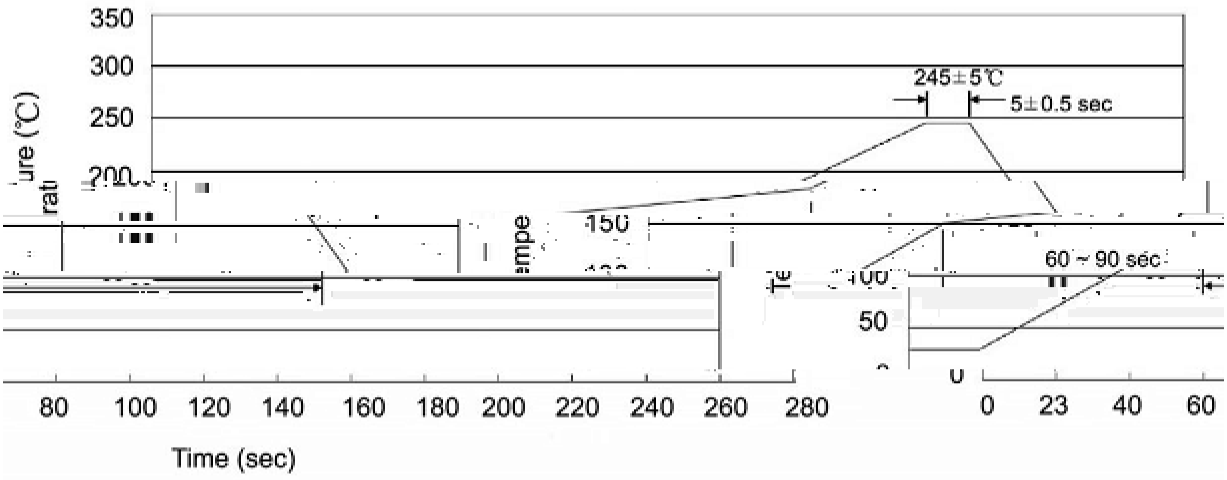
ب ˝ χ

EU χ	Ɦѫ ʒ ᴎ Ꞃƀ
0Y6378 χ	Ɜѫ ғ ᵝ ʒ ᴺ
FW:	Ɜѫ ɲ ɥɦ ɺ ═
---- χ	Ɜѫ ꞁ ғ ἤ ᴺ Ꞃƀ ɩ ɞ ꞁ ғ ἤ ᴺ ψ ק

Note:

BR:	Company Code
0Y6378 χ	Product Type.
FW:	Internal Structure
****:	Lot No. Code, code change with Lot No.

(   ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



ب ˝ χ
1 ĺ ♬ □ ŷ 25 Ḱ 150 ł ι `H ڗ 60 Ḱ 90sec;
2 Š Ӫ □ ŷ 245 ° 5 ł ι `H ڗ 'Y ﾑ ㎿ 5 ° 0.5sec;
3 ì˙ ү˛ ɔ ঌ ŷ ㎿ 2 Ḱ 10 ł /sec.

Note:
1.Preheating:25~150 ł , Time:60~90sec.
2.Peak Temp.:245 ° 5 ł , Duration:5 ° 0.5sec.
3. Cooling Speed: 2~10 ł /sec.

/ Resistance to Soldering Heat Test Conditions

□ ŷ χ 260 ° 5 ł   `H ڗ χ 10 ° 1 sec.

Temp.:260±5   Time:10±1 sec

/ Packaging SPEC.

ი` γ Ŀ / REEL

Package Type	Units					Dimension (unit mm^3)		
	Units/Reel /	Reels/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Reel	Inner Box	Outer Box
TO-263	800	1	800	5	4,000	13 ×24	360×360×50	385×257×392